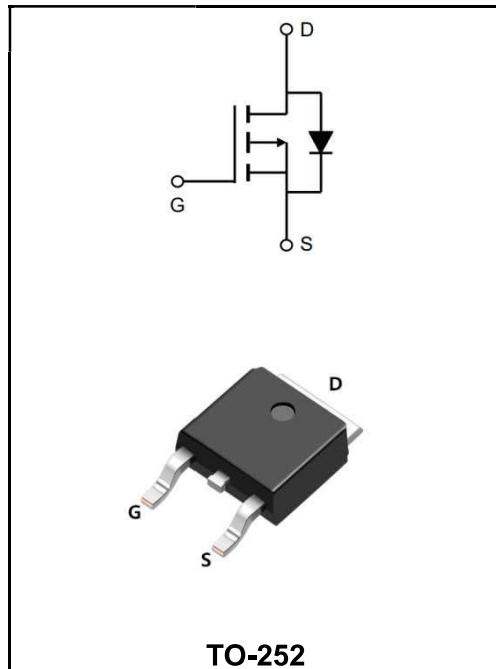


-12V P-CHANNEL ENHANCEMENT MODE MOSFET
MAIN CHARACTERISTICS

I_D	-90A
V_{DSS}	-12V
$R_{DS(on)-typ}(@V_{GS} = -4.5V)$	< 4.5mΩ (Type: 3.5 mΩ)


Application

- ◆ Battery protection
- ◆ Load switch
- ◆ Uninterruptible power supply

Product Specification Classification

Part Number	Package	Marking	Pack
YFW90P01AD	TO-252	YFW 90P01AD XXXXX	2500PCS/Tape

Maximum Ratings at $T_c=25^\circ\text{C}$ unless otherwise specified

Characteristics	Symbols	Value	Units
Drain-Source Voltage	V_{DS}	-12	V
Gate - Source Voltage	V_{GS}	± 12	V
Continuous Drain Current, $V_{GS} @ 10V^1$ @ $T_c=25^\circ\text{C}$	I_D	-90	A
Continuous Drain Current, $V_{GS} @ 10V^1$ @ $T_c=100^\circ\text{C}$	I_D	-54	A
Drain Current- Pulsed ¹	I_{DM}	-240	A
Avalanche Current	I_{AS}	50	A
Single Pulsed Avalanche Energy	E_{AS}	560	mJ
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	°C
Thermal Resistance Junction-Ambient	$R_{\theta JA}$	62.5	°C/W
Thermal Resistance Junction-Case	$R_{\theta JC}$	3	°C/W

Maximum Ratings at T_c=25°C unless otherwise specified

Characteristics	Test Condition	Symbols	Min	Typ	Max	Units
Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =-250uA	BV _{DSS}	-12	-18	-	V
BVDSS Temperature Coefficient	Reference to 25°C , I _D =-1mA	ΔBV _{DSS/ΔTJ}	-	-0.008	-	V/°C
Static Drain-Source On-Resistance	V _{GS} =-4.5V, I _D =-20A	R _{DS(ON)}	-	3.5	4.5	mΩ
	V _{GS} =-2.5V, I _D =-20A		-	4.8	6.0	
Gate -Threshold Voltage	V _{DS} =V _{GS} , I _D =-250uA	V _{GS(th)}	-0.4	-0.6	-1.0	V
V _{GS(th)} Temperature Coefficient		ΔV _{GS(th)}	-	-3.44	-	mV/°C
Drain-Source Leakage Current	V _{DS} =-20V , V _{GS} =0V , T _J =25°C	I _{DSS}	-	-	-1	μA
	V _{DS} =-16V , V _{GS} =0V , T _J =125°C		-	-	-30	
Gate –Source Leakage Current	V _{GS} =±12V, V _{DS} =0V	I _{GSS}	-	-	±500	nA
Forward Transconductance	V _{DS} =-10V , I _S =-3A	g _{fs}	-	30	-	S
Total Gate Charge	V _{DS} =-16V V _{GS} =-4.5V I _D =-5A	Q _g	-	149	225	nC
Gate-Source Charge		Q _{gs}	-	14.4	22	
Gate-Drain Charge		Q _{gd}	-	42.8	65	
Turn-on delay time	V _{DD} =-15V V _{GS} =-4.5V I _D = -1A R _G =25	t _{d(on)}	-	21.2	42	ns
Rise Time		T _r	-	20.6	40	
Turn-Off Delay Time		t _{d(OFF)}	-	26	52	
Fall Time		t _f	-	400	600	
Input Capacitance	V _{DS} =-15V V _{GS} =0V f=1MHz	C _{iss}	-	6800	-	pF
Output Capacitance		C _{oss}	-	769	-	
Reverse Transfer Capacitance		C _{rss}	-	726	-	
Gate resistance	V _{GS} =0V, V _{DS} =0V, F=1MHz	R _g	-	2.6	-	Ω
Continuous Source Current	V _G =V _D =0V , Force Current	I _s	-	-	-90	A
Pulsed Source Current		I _{SM}	-	-	-180	A
Diode Forward Voltage	V _{GS} =0V , I _s =1A , T _J =25°C	V _{SD}	-	-	-1	V

Note :

1. The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
2. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
3. The EAS data shows Max. rating . The test condition is VDD=8V,VGS=4.5V,L=0.1mH,IAS =50A
4. The power dissipation is limited by 150°C junction temperature
5. The data is theoretically the same as I D and I DM , in real applications , should be limited by total power dissipation.

Ratings and Characteristic Curves

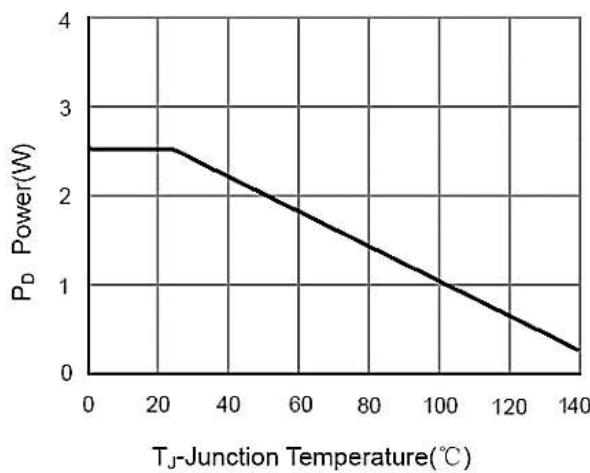


Figure 1: Power Dissipation

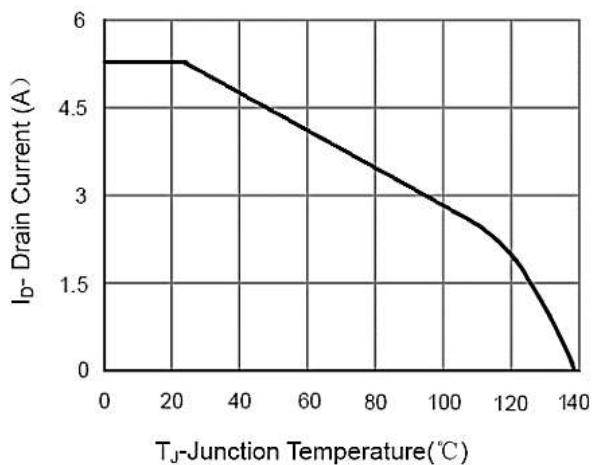


Figure 2: Drain Current

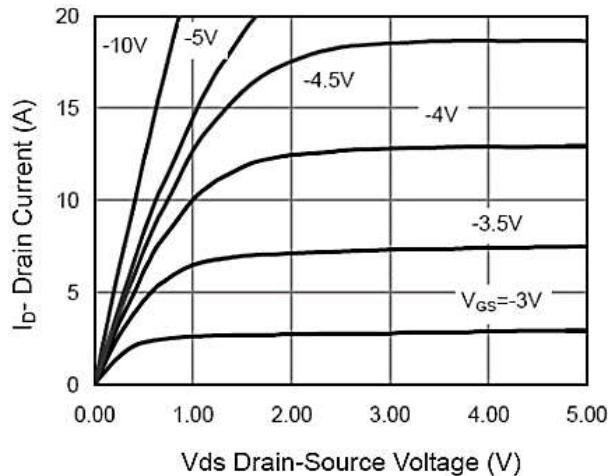


Figure 3: Output Characteristics

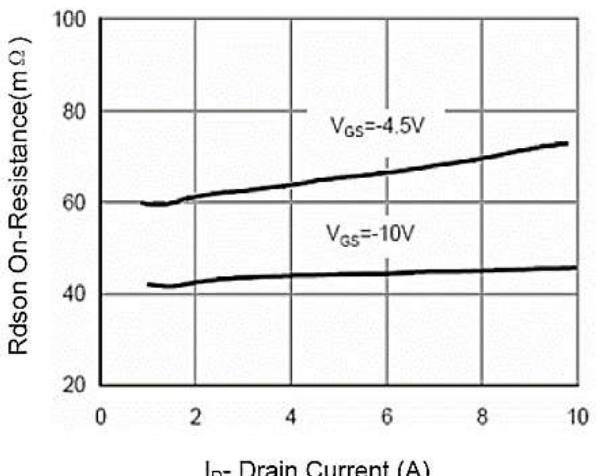


Figure 4: Drain-Source On-Resistance

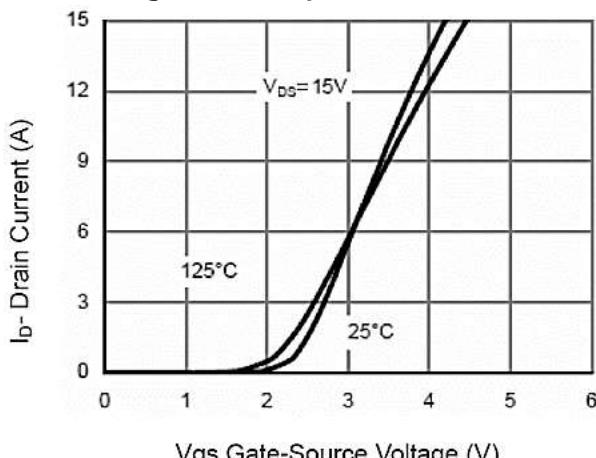


Figure 5: Transfer Characteristics

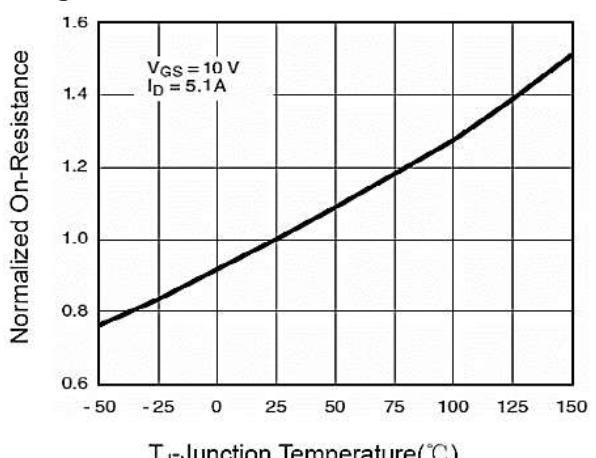


Figure 6: Drain-Source On-Resistance

Ratings and Characteristic Curves

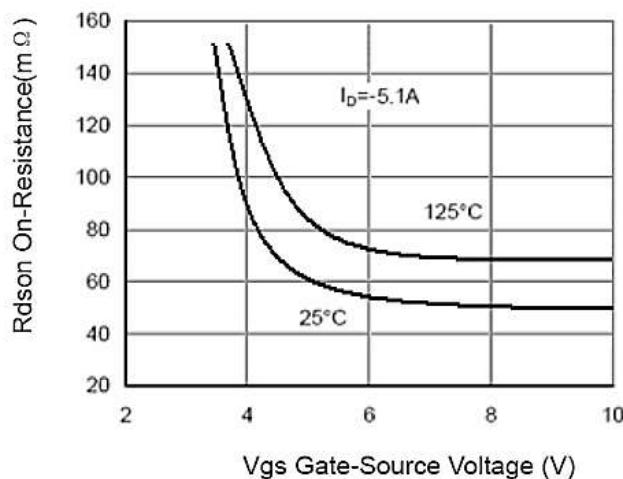


Figure 7: $R_{DS(on)}$ vs V_{GS}

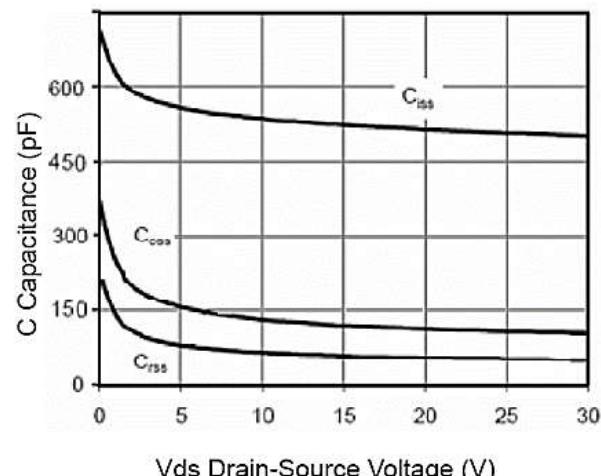


Figure 8: Capacitance vs V_{DS}

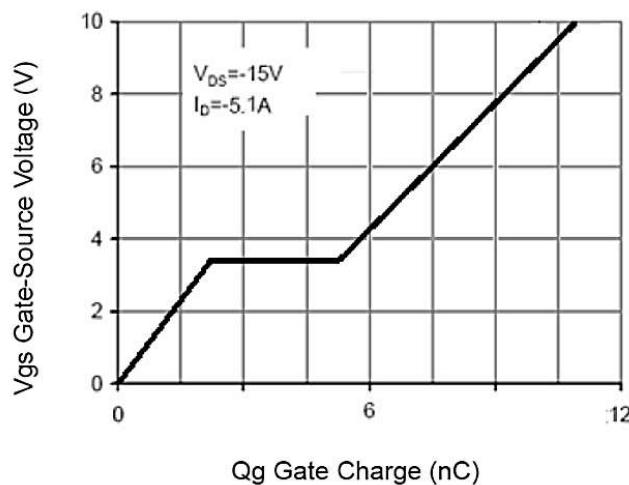


Figure 9: Gate Charge

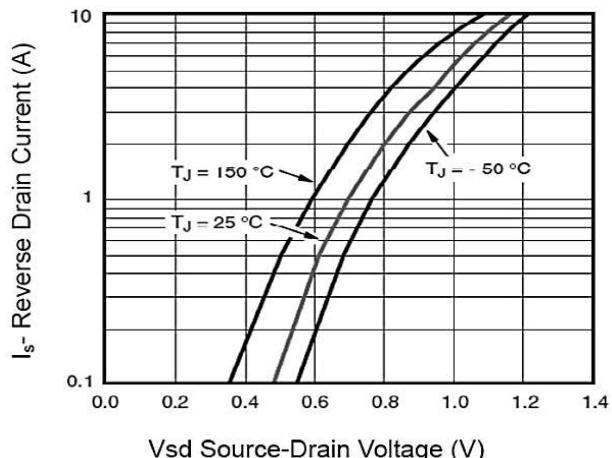


Figure 10: Source-Drain Diode Forward

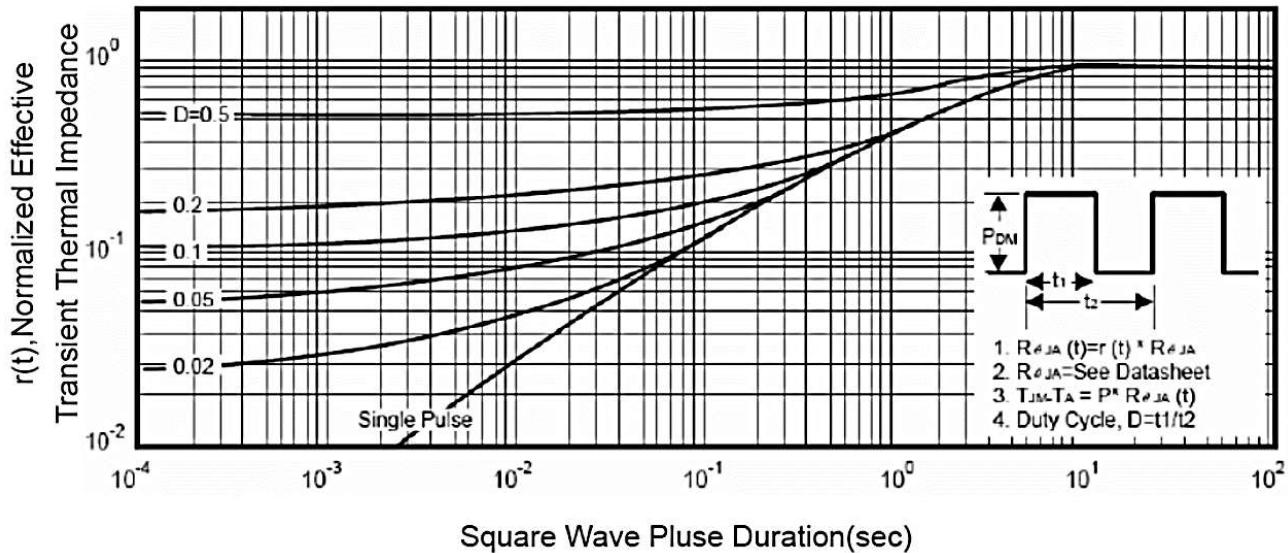


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Case

Package Outline Dimensions Millimeters

TO-252

Dim.	Min.	Typ.	Max.
A	2.10	-	2.50
A2	0	-	0.10
B	0.66	-	0.86
B2	5.18	-	5.48
C	0.40	-	0.60
C2	0.44	-	0.58
D	5.90	-	6.30
D1	5.30REF		
E	6.40	-	6.80
E1	4.63	-	-
G	4.47	-	4.67
H	9.50	-	10.70
L	1.09	-	1.21
L2	1.35	-	1.65
V1	-	7°	-
V2	0°	-	6°

All Dimensions in millimeter